L Number	Hits	Search Text	DB	Time stamp
1	6088	((Chip or die or wafer) with Mirror)	USPAT	2003/10/05 13:43
2	802	(((Chip or die or wafer) with Mirror)) and (Wafer same (cut or saw or singulate))	USPAT	2003/10/05 15:53
3	694	((((Chip or die or wafer) with Mirror)) and (Wafer same (cut or saw or singulate))) and (@ad<20000510)	USPAT	2003/10/05 15:17
4	40	(((((Chip or die or wafer) with Mirror)) and (Wafer same (cut or saw or singulate))) and (@ad<20000510)) and ((photoresist or resist)with Mirror)	USPAT	2003/10/05 13:44
5	40	(((((Chip or die or wafer) with Mirror)) and (Wafer same (cut or saw or singulate))) and (@ad<20000510)) and ((photoresist or resist) with Mirror)	USPAT	2003/10/05 15:51
6	2	6063696.URPN.	USPAT	2003/10/05 14:08
7	2	6063696.URPN.	USPAT	2003/10/05 14:26
8	12	("5107328" | "5435876" | "5516728" | "5605489" | "5766367" | "5872046" | "5923995" | "5951813" | "5958510" | "5963788" | "6025767" | "6063696").PN.	USPAT	2003/10/05 14:28
9	14	((((Chip or die or wafer) with Mirror)) and (Wafer same (cut or saw or singulate))) and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:06
10	3	438/465.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:11
11	5	438/465.ccls. and ((photoresist or resist or protective) with (Mirror))	USPAT	2003/10/05 15:08
12	0	438/114.ccls. and ((photoresist or resist or protective) with (Mirror))	USPAT	2003/10/05 15:08
13	3	438/460.ccls. and ((photoresist or resist or protective) with (Mirror))	USPAT	2003/10/05 15:09
14	24	((photoresist or resist or protective) with (Mirror and (wire or wirebond)))	USPAT	2003/10/05 15:09
15	2	(((photoresist or resist or protective) with (Mirror and (wire or wirebond)))) and (Wafer same (cut or saw or singulate))	USPAT	2003/10/05 15:09
16	20	(((photoresist or resist or protective) with (Mirror and (wire or wirebond)))) and (@ad<20000510)	USPAT	2003/10/05 15:10
17	1	257/414.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:12
18	34	257/$.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))	USPAT	2003/10/05 15:12
19	25	(257/$.ccls. and ((photoresist or resist or protective) with (Mirror and (remove or removal)))) and (@ad<20000510)	USPAT	2003/10/05 15:42
20	1	("20010041381").PN.	US-PGPUB	2003/10/05 15:45
21	0	antisitcking with photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 15:46
22	1	antisticking with photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 15:46

23	5	antisticking same (photoresist or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 15:48
24	5	(antisticking or antistck) same (photoresist or resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 15:49
25	0	((antisticking or antistck) same (photoresist or resist)) not (antisticking same (photoresist or resist))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/05 15:50
26	0	("6507082").PN.	US-PGPUB	2003/10/05 15:50
27	1	("6507082").PN.	USPAT	2003/10/05 15:50
28	0	6507082.URPN.	USPAT	2003/10/05 15:51
29	0	6507082.URPN.	USPAT	2003/10/05 15:51
30	0	6507082.URPN.	USPAT	2003/10/05 15:51
31	116	(wire or wirebond) and ((photoresist or resist) with Mirror)	USPAT	2003/10/05 15:52
32	26	((wire or wirebond) and ((photoresist or resist) with Mirror)) and (Wafer same (cut or saw or singulate))	USPAT	2003/10/05 15:53